Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP FF 12908E Switch Chassis(JH255A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing> 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing		0

radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove all of the labels(part 1);
2. Unscrew the screws on part 2, and then remove part 2;
3. Unscrew the screws on part 3, and then remove part 3;
4. Unscrew the screws on part 4, and then remove part 4;
5. Remove part 5;
6. Remove part 6;
7. Unscrew the captive-screws on part 7, and then remove part 7 from part 8;
8. Remove the shielding fingers 3-1 from part 3;
9. Remove the film 3-2 from part 3;
10. Remove the shielding fingers 4-1 from part 4;
11. Remove the film 4-2 from part 4;
12. Remove the spring bottom 5-1 from part 5;
13. Remove the shielding fingers 6-1 from part 6;
14. Unscrew the screws on part 7-1, and then remove part 7-1 from part 7;
15. Unscrew the screws on part 7-2, and then remove part 7-2 from part 7;
16. Unscrew the screws,and then disassemble part 7-2;
17. Remove all the cables inside part 8.
18. Unscrew the screws on part 8-1, and then remove part 8-1 from part 8;
19. Unscrew the screws on part 8-2,and then pull out part 8-2 from part 8;
20. Remove the insulating film and shielding fingers from part 8-2.
21. Unscrew the screws on part 8-3, and then remove part 8-3 from part 8;
22. Unscrew the screws on pcb 8-4, and then remove pcb 8-4 from part 8;
23. Unscrew the screws on part 8-5, and then remove part 8-5 from part 8;
24. Unscrew the screws on part 8-6, and then remove part 8-6 from part 8;
25. Remove the shielding fingers 8-7-1 from part 8-7;
26. Remove the insulating film 8-7-2 from part 8-7;
27. Unscrew the screws on part 8-7-3, and then remove them from 8-7;
28. Unscrew guide pins 8-7-4, and then remove them from 8-7;
29. Unscrew the screws on guide pins 8-7-5, and then remove them from 8-7;
30. Unscrew the screws on part 8-7-6, and then remove it from 8-7.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

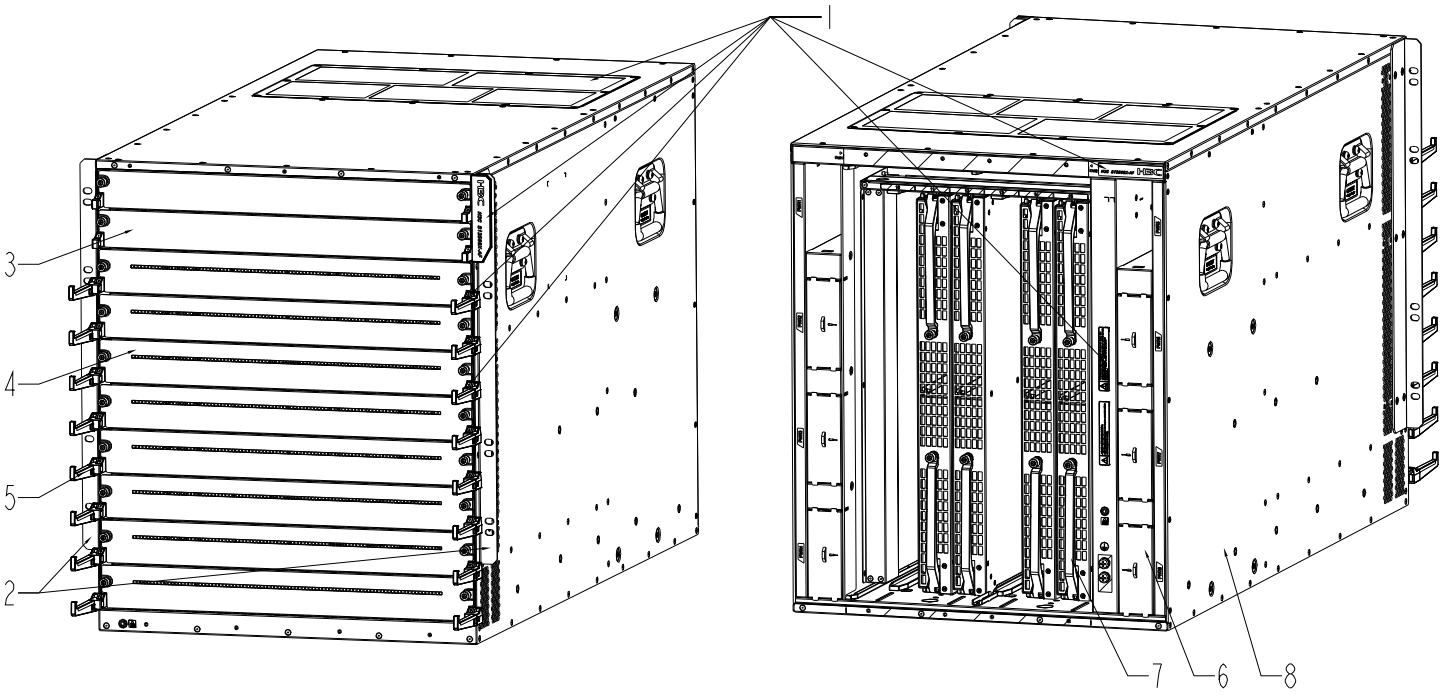


Figure 1Front view of the product Figure 2Rear view of the product

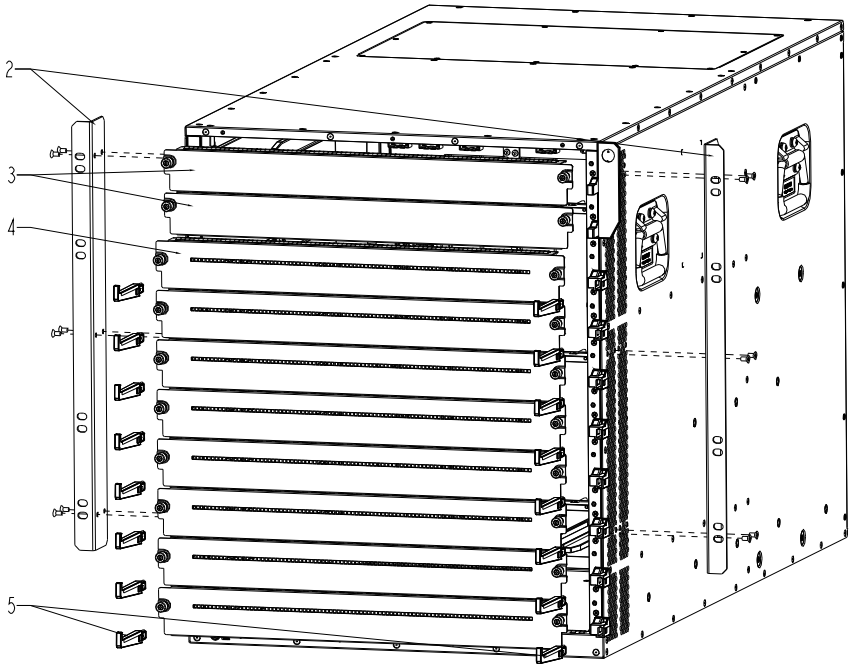


Figure 3Treatments to the product

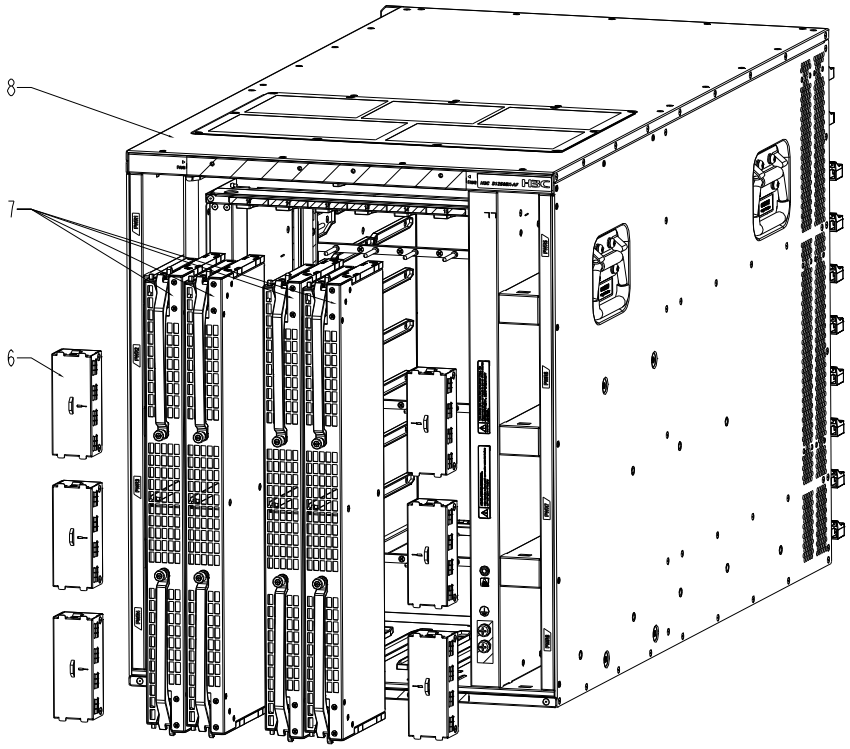
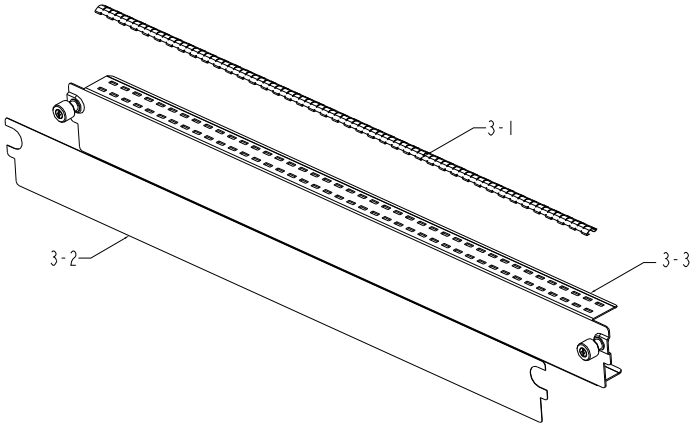


Figure 4Treatments to the product



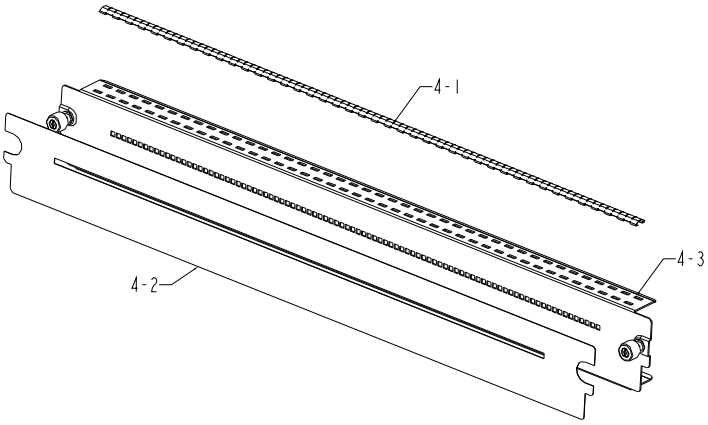


Figure 5Treatments to the part 3Figure 6 Treatments to the part 4

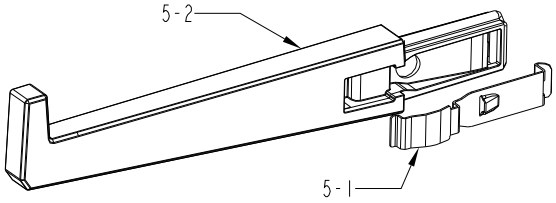


Figure7 Treatments to the part 5

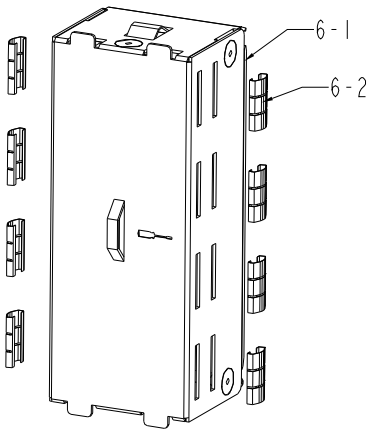


Figure 8Treatments to the part 6

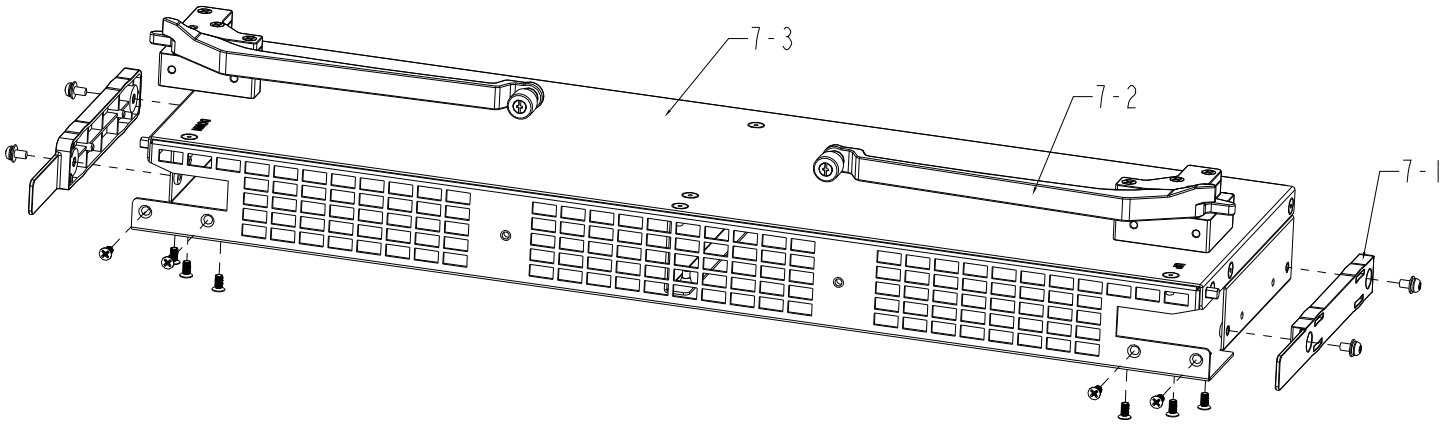


Figure 9Treatments to the part 7

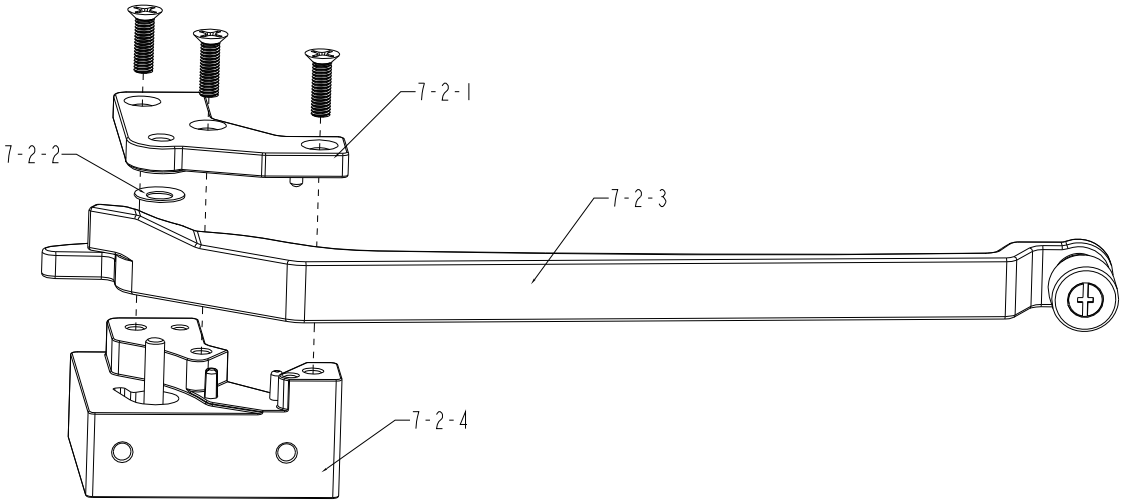


Figure10Treatments to the part 7-2

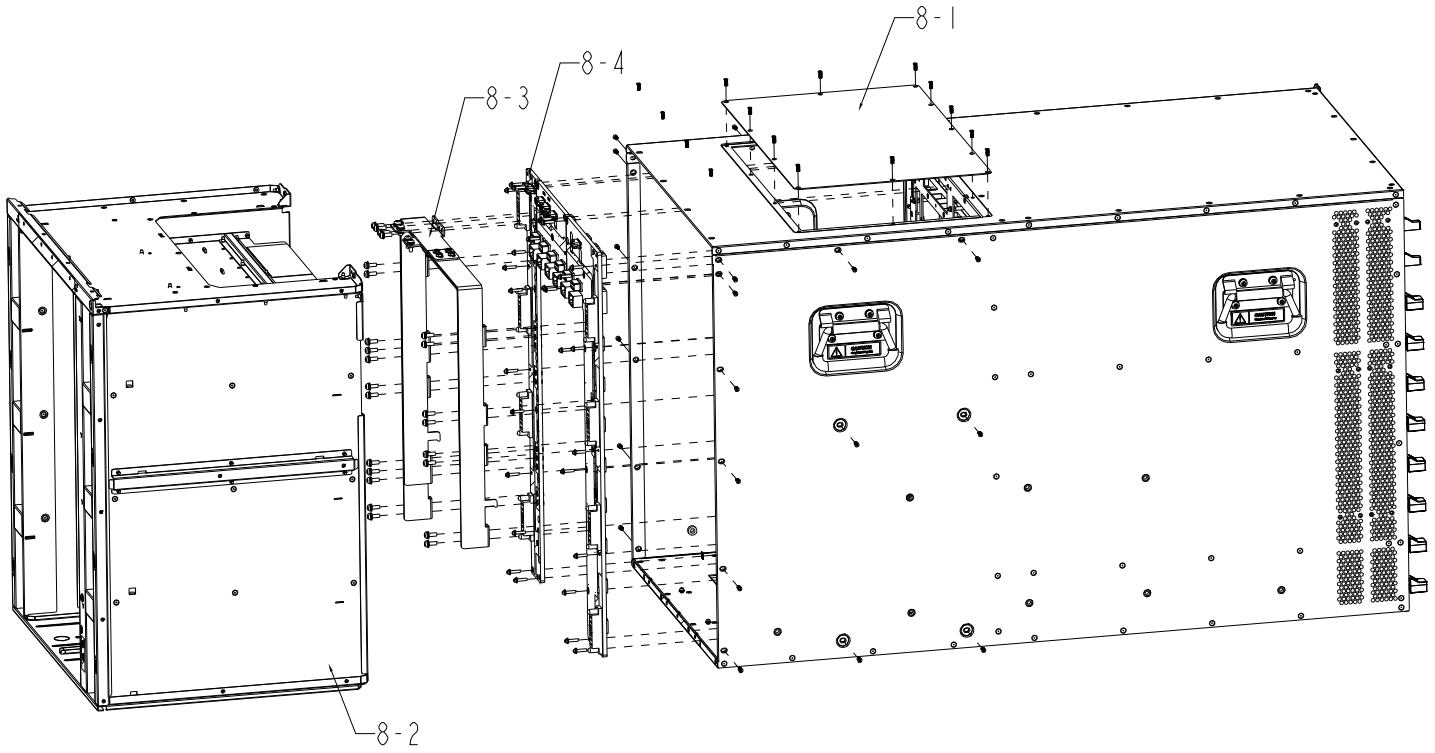


Figure11 Treatments to the part 8

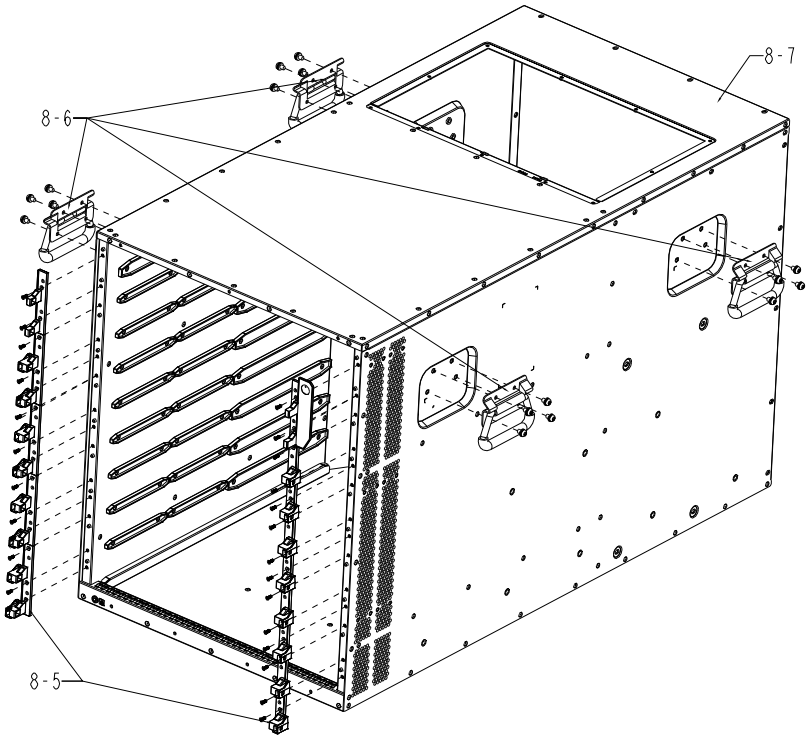


Figure12 Treatments to the part 8

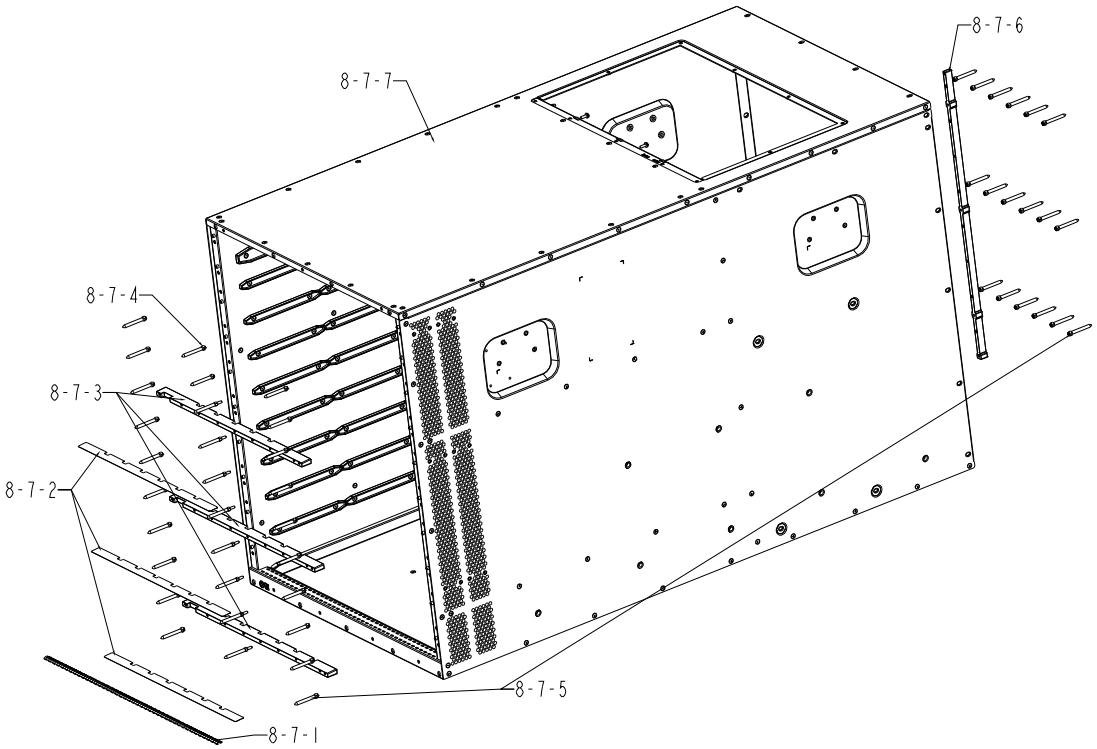


Figure13 Treatments to the part 8-7

3.3 Material of the facility built

Facility	Components	Material	Weight(g) *(PCS)	Weight percentage	Selective treatment for materials andcomponents	Details
1		Pla	30*1	0.04%		Pla recycling
2		Fe	424*2	1.15%		Fe recycling
3						
	3-1	Cu, Be	3*2	0.01%		CuBe recycling
	3-2	Pla	5*2	0.01%		Pla recycling
	3-3	Fe	225*2	0.61%		Fe recycling
4						
	4-1	Cu, Be	3*8	0.03%		CuBe recycling
	4-2	Pla	6*8	0.06%		Pla recycling
	4-3	Fe	237*8	2.57%		Fe recycling
5						
	5-1	Fe	0.5*16	0.01%		Fe recycling
	5-2	Zn	9*16	0.19%		Zn recycling
6				0.00%		
	6-1	Fe	1*6	0.01%		Fe recycling
	6-2	Cu, Be	84*6	0.68%		CuBe recycling
7						
	7-1	Pla	30*6	0.24%		Pla recycling
	7-2	Zn, Fe	336*6	2.73%		Zn recycling
	7-3	Fe	1214*6	9.86%		Fe recycling
8						
	8-1	Fe	721*1	0.98%		Fe recycling
	8-2	Fe	13038	17.64%		Fe recycling
	8-3	Cu	943*1	1.28%		Cu recycling
	8-4	Complex PCB(3 PCS)	1490*1	2.02%	The surface of PCB is greater than 10 square centimeters;	
	8-5	Zn	77*10	1.04%		Zn recycling
	8-6	Fe, Pla	149*4	0.81%		Fe Pla recycling

	8-7					
	8-7-1	Cu, Be	3*1	0.00%		Cu Be recycling
	8-7-2	Pla	4*3	0.02%		Pla recycling
	8-7-3	Al	79*3	0.32%		Al recycling
	8-7-4	Fe	4*8	0.04%		Fe recycling
	8-7-5	Fe	3*40	0.16%		Fe recycling
	8-7-6	Al	61*1	0.08%		Al recycling
	8-7-7	Fe, Zn	42420*1	57.40%		Fe Zn recycling

4. Revised record

Date	Version	Author	Modify content
2015.05.11	V0	Chen Linwei	Initial version